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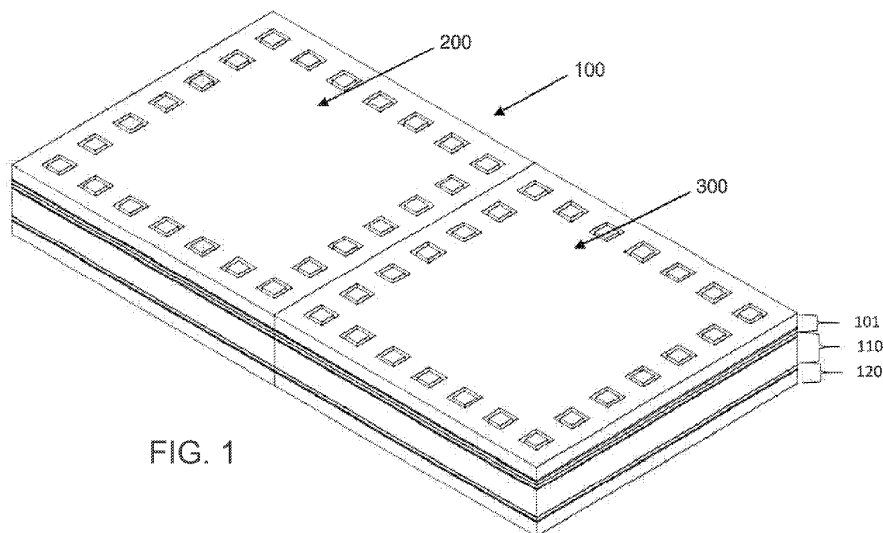


FIG. 1

(57) Abstract: The present disclosure relates to a MEMS inertial sensor device having a plurality of accelerometers formed in a semiconductor chip package wherein the accelerometers are formed in a conductive single crystal silicon SOI wafer bonded to a cap wafer having a hermetic seal. Inertial sensor chip packages can include integrated circuits configured to process inertial sensor data.

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